

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes a substrate, a chip and a marking film. The semiconductor chip is electrically connected to the substrate. A marking film is formed on the back surface of the chip. Thereby, a mark is formed by patterning the marking film. Generally, the marking film is a dry film or a tape. Not only the marking film prevents the singulated chips from being in a fry-chip manner but also can be patterned by laser ablation instead of the conventional method of forming a mark directly on the back surface of the chip. Accordingly, the chip will be prevented from destroying in the duration of performing the marking process.